

Method of Forming a Dual Damascene Via by Using a Metal Hard Mask Layer

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ABSTRACT OF THE INVENTION

This invention relates to a method of forming a dual damascene via, in particular to a method of forming a dual damascene via by using a metal hard mask layer. The present invention uses a metal layer to be a
10 hard mask layer to make the surface of the isolation layer become a level and smooth surface and not become a rounding convex and to prevent the via being connected with others vias to cause the leakage defects after forming the shape of the via.

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